

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
DPAC Technologies Corp.	06/09/2004

RECEIVING PARTY DATA

Name:	Staktek Group L.P.
Street Address:	8900 SHOAL CREEK BLVD.
Internal Address:	SUITE 125
City:	Austin
State/Country:	TEXAS
Postal Code:	78701

PROPERTY NUMBERS Total: 8

Property Type	Number
Patent Number:	6222737
Patent Number:	6404043
Patent Number:	6426549
Patent Number:	6473308
Patent Number:	6544815
Patent Number:	6627984
Patent Number:	6660561
Patent Number:	RE39628

CORRESPONDENCE DATA

Fax Number: (512)906-2075
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
 Phone: (512) 906-2201
 Email: lauff@civinsdenko.com
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 Address Line 1: 816 Congress Ave., Suite 1205

OP \$320.00 6222737

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**PATENT
 REEL: 023870 FRAME: 0245**

Address Line 2: Civins Denko Coburn & Lauff LLP
Address Line 4: Austin, TEXAS 78701

ATTORNEY DOCKET NUMBER:	21260
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NAME OF SUBMITTER:	Steven Lauff
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Total Attachments: 10 source=46#page1.tif source=46#page2.tif source=46#page3.tif source=46#page4.tif source=46#page5.tif source=46#page6.tif source=46#page7.tif source=46#page8.tif source=46#page9.tif source=46#page10.tif
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06/08/04

EXHIBIT A
ASSIGNMENT OF DPAC ASSETS

WHEREAS, DPAC Technologies Corp. (formerly known as Dense-Pac Microsystems, Inc.) ("DPAC") owns certain intellectual properties consisting of inventions, patents, and patent applications (enumerated on attached and incorporated Exhibit 1) (the "DPAC Assets");

WHEREAS, Staktek Group L.P., a Texas limited partnership, desires to acquire and DPAC desires to assign to Staktek Group L.P., all of DPAC's rights in the DPAC Assets;

NOW, THEREFORE, DPAC, for itself and its predecessors in interest for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, does hereby ASSIGN to Staktek Group L.P., all right, title and interest in the DPAC Assets, this assignment including, but not being limited to:

1. The ASSIGNED INVENTIONS enumerated on Exhibit 1 whether created by DPAC, its predecessors, its legal representatives or its assigns in the United States or any other country or place anywhere in the world;
2. The ASSIGNED PATENTS enumerated on Exhibit 1;
3. The ASSIGNED PATENT APPLICATIONS enumerated on Exhibit 1;
4. All rights of action on account of past, present, and future unauthorized use or infringement of said DPAC Assets including, but not limited to all rights to damages so accrued;
5. The right, where allowed by law, to file in the name of Staktek Group L.P. applications for patent and like protection for any one or more of the DPAC Assets in any country or countries foreign to the United States;
6. All international and domestic rights or priorities associated with any one of the DPAC Assets; and

This Assignment shall be binding upon and shall inure to the benefit of the successors, assigns, and legal representatives of the parties.

DPAC	<i>CR</i>
STAKTEK	_____

PATENT

06/08/04

EXECUTED on the EFFECTIVE DATE indicated below:

Assignor: DPAC TECHNOLOGIES CORP.

Date: JUNE 9, 2004

By: [Signature]
[DPAC TECHNOLOGIES CORP OFFICER]

Name: CREIGHTON K. EARLY

Title: CHIEF EXECUTIVE OFFICER

THE STATE OF Calif]

COUNTY OF Orange]

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§
§

This instrument was acknowledged by DPAC Officer on this the 9 day of June, 2004.

(Seal)

[Signature]
Notary Public in and for the State of []

My commission expires: 9/25/04

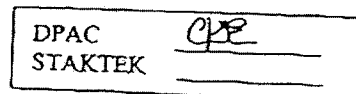
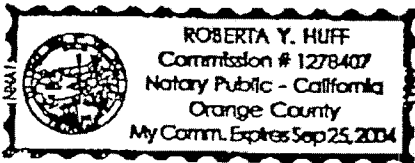


EXHIBIT 1 - DPAC Assets

06/09/04

Case	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required and Owner	Date Required Action Assigned
DENSE-002A	Universal Package and Method of Forming the Same	Patent	Original	4/23/1999	09/298,664	4/24/2001	6,222,737	Universal Package and Method of Forming the Same	Issued, 3 1/2 year maintenance fees due 10/24/04.	N/A	None
DENSE-002G	Universal Package and Method of Forming the Same	Patent	Divisional	9/19/2000	09/664,938	3/26/2002	6,360,433	Universal Package and Method of Forming the Same	Issued, 3 1/2 year maintenance fees due 09/26/05.	N/A	None
DENSE-003A	Stackable Chip Package with Flex Carrier	Patent	Original	1/13/2000	09/482,294	7/21/2001	6,262,895	Stackable Chip Package with Flex Carrier	Issued, 3 1/2 year maintenance fees due 01/17/05.	N/A	None
DENSE-003C	Stackable Chip Package with Flex Carrier	Patent	Continuation	4/10/2001	09/038,773	10/29/2002	6,473,308	Stackable Chip Package with Flex Carrier	Issued, 3 1/2 year maintenance fees due 04/29/2006.	N/A	None
DENSE-005A	CSP Stacking Technology Using Rigid/Flex Construction	Patent	Original	3/24/2000	09/535,641	8/20/2002	6,417,433 B1	CSP Stacking Technology Using Rigid/Flex Construction	Issued, 3 1/2 year maintenance fees due 02/20/2006.	PTO	None
DENSE-012A	Mechanically Registered and Interconnected Chip Stack	Patent	Original	6/15/2000	09/594,989			Mechanically Registered and Interconnected Chip Stack	Closed.	N/A	None
DENSE-012C	Mechanically Registered and Attachable Chip Stack	Patent	Divisional	7/24/2002	10/202,185			Mechanically Registered and Attachable Chip Stack	Issued, 3 1/2 year maintenance fee due 12/09/2006	PTO	None
DENSE-013A	Chip Stack and Method of Making Same	Patent	Original	4/13/1995	08/421,801	3/18/1997	5,612,570	Chip Stack and Method of Making Same	Issued, 7 1/2 year maintenance fee due 09/18/2004.	N/A	None
ISE-013PC	Chip Stack and Method of Making Same	Patent	PCT					Chip Stack and Method of Making Same	Closed.	N/A	None
DENSE-015A	Modular Panel Stacking Process	Patent	Original	11/17/1997	08/971,499	02/09/1999	5,869,353	Modular Panel Stacking Process	Issued, 7 1/2 year maintenance fee due 08/09/2007.	N/A	None
DENSE-015X	Restorer, Modular Panel Stacking Process	Patent	Original	8/2/2000	09/633,297			Modular Panel Stacking Process	Awaiting Reply re: Non-Recordation of Document	PTO	None
DENSE-016A	IC Chip Package Having Chip Attached to and Wire Bonded within an Overlying Substrate	Patent	Original	07/851,755				IC Chip Package Having Chip Attached to and Wire Bonded within an Overlying Substrate	Closed.	N/A	None

AUS:537564.4

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Updated: January 28, 2004

EXHIBIT 1 - DPAC Assets

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Case	Title/Mark - Invention	Idea Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required and Owner	Date Required Action Assigned
DENSE-016EP	IC Chip Package and Method of Making the Same	Patent	European		93908306,9			IC Chip Package and Method of Making the Same	Closed.	N/A	None
DENSE-016JP	IC Chip Package and Method of Making the Same	Patent	Japan		5-516611			IC Chip Package and Method of Making the Same	Closed.	N/A	None
DENSE-016TC	IC Chip Package and Method of Making the Same	Patent	PCT	3/10/1993	PCT/US93/02202			IC Chip Package and Method of Making the Same	Closed.	N/A	None
DENSE-016G	IC Chip Package Having Chip Attached to and Wire Bonded within an Overlying Substrate	Patent	Divisional	7/29/1992	07/920,763	5/17/1994	5,313,096	IC Chip Package having Chip Attached to and Wire Bonded within an Overlying Substrate	Issued, 1 1/2 year maintenance fee due 11/17/2005.	N/A	None
DENSE-017A	Stackable Flex Circuit IC Package and Method of Making Same	Patent	Original	5/5/1999	09/305,394	11/27/2001	6,323,060 B1	Stackable Flex Circuit IC Package and Method of Making Same	Issued, 3 1/2 year maintenance fee due 05/27/2005.	N/A	None
DENSE-017EP	Stackable Flex Circuit IC Package and Method of Making Same	Patent	European	10/26/2001	932131,6			Stackable Flex Circuit IC Package and Method of Making the Same	Closed.	FTO	None
DENSE-017HK	Stackable Flex Circuit IC Package and Method of Making Same	Patent	Hong Kong	9/23/2002	1045759			Stackable Flex Circuit IC Package and Method of Making Same	** Closed.	FTO	None
DENSE-017JP	Stackable Flex Circuit IC Package and Method of Making Same	Patent	Japan	10/29/2001	2000-616064			Stackable Flex Circuit IC Package and Method of Making the Same	** Closed.	DPAC	5/5/2007
SE-017KS	Stackable Flex Circuit IC Package and Method of Making Same	Patent	Korea	11/3/2001	2001-7014056			Stackable Flex Circuit IC Package and Method of Making the Same	** Closed.	DPAC	5/5/2005
DENSE-017PC	Stackable Flex Circuit IC Package and Method of Making Same	Patent	PCT	5/5/2000	PCT/US00/12393			Stackable Flex Circuit IC Package and Method of Making Same	Closed.	N/A	None
DENSE-017B	Stackable Flex Circuit Chip Package and Method of Making Same	Patent	Continuation-in-Part	5/19/2000	09/574,321	2/26/2002	6,351,029 B1	Flex Wrap Carrier and Method	Issued, 3 1/2 year maintenance fees due 08/26/2005.	N/A	None
DENSE-017BPC	Stackable Flex Circuit Chip Package and Method of Making Same	Patent	PCT	3/29/2001	PCT/US01/10064			Stackable Flex Circuit Chip Package and Method of Making Same	Closed.	N/A	None

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Case	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required by Owner	Date Requested Action Assigned
DENSE-017BTT	Stackable Flex Circuit Chip Package and Method of Making Same	Patent	Taiwan	4/24/2001	90109731			Stackable Flex Circuit Package and Method of Making Same	Closed.	PTO	None
DENSE-017B1	Flex Wrap Carrier and Method	Patent	Continuation-in-Part					Flex Wrap Carrier and Method	Closed, pursuant to client instructions.	N/A	None
DENSE-017BQ	Stackable Flex Circuit Package and Method of Making Same	Patent	Divisional	6/25/2001	09/888,785	7/30/2002	6426240 B1	Stackable Flex Circuit Package and Method of Making Same	Issued, 3 1/2 year maintenance fees due 01/30/2006.	N/A	None
DENSE-017C	Stackable Flex Circuit Chip Package and Method of Making Same	Patent	Continuation	6/25/2001	09/888,792	2/4/2003	6,514,793	Stackable Flex Circuit Chip Package and Method of Making Same	Issued, 3 1/2 year maintenance fees due 08/04/2006.	N/A	None
DENSE-017D	Stackable Flex Circuit and Method of Making Same	Patent	Divisional	11/3/2000	09/706,015	7/30/2002	6,426,549 B1	Stackable Flex Circuit and Method of Making Same	Issued, 3 1/2 year maintenance fees due 01/30/2006.	N/A	None
DENSE-018A	Chip Stack and Method of Making Same	Patent	Original	5/5/1998	09/073,254	1/30/2001	6,180,441 B1	Chip Stack and Method of Making Same	Issued, 3 1/2 year maintenance fees due 07/30/2004.	N/A	None
DENSE-018EP	Chip Stack and Method of Making Same	Patent	European	11/14/2000	99920334.2			Chip Stack and Method of Making Same	Closed.	N/A	None
DENSE-018FP	Chip Stack and Method of Making Same	Patent	Japan	10/31/2000	2000-547656			Chip Stack and Method of Making Same	** Closed.	FTO	None
DENSE-018KS	Chip Stack and Method of Making Same	Patent	Korea	11/6/2000	2000-7012384			Chip Stack and Method of Making Same	Closed.	DPAC	5/4/2004
DENSE-018PC	Chip Stack and Method of Making Same	Patent	PCT		PCT/US99/09744			Chip Stack and Method of Making Same	Closed.	N/A	None
DENSE-019A	Module and Method of Making Same	Patent	Original					Module and Method of Making Same	Unified - Closed.	N/A	None
DENSE-020A	Chip Stack Having Interconnected Bonding Pads on Staggered Edges of Chips	Patent	Original		08/083,092			Chip Stack Having Interconnected Bonding Pads on Staggered Edges of Chips	Closed.	N/A	None


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Case	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required	Date Required Action Assigned
DENSE-021A	IC Chip Stack and Method of Making	Patent	Original		08/119,518			IC Chip Stack and Method of Making Same	Closed.	N/A	None
DENSE-022A	Memory Module Having Memory Package	Patent	Original		08/083,068			Memory Module Having Memory Package Same	Closed.	N/A	None
DENSE-023A	Chip Stack and Method of Making Same	Patent	Original		08/935,276			Chip Stack and Method of Making Same	Closed.	N/A	None
DENSE-023G	Chip Stack and Method of Making Same	Patent	Divisional		08/097,449			Chip Stack and Method of Making Same	Closed.	N/A	None
DENSE-023A	Externally Configurable Chip Carrier	Patent	Original		07/552,578			Externally Configurable Chip Carrier	Closed.	N/A	None
DENSE-026A	Chip Stack with Active Cooling System	Patent	Original	7/15/2000	09/594,563	5/22/2001	6,236,565 B1	Active Cooling System for Chip Stack	Issued. 3 1/2 year maintenance fees due 11/22/2004.	DPAC	None
DENSE-027A	Chip Stack with Differing Chip Package Types	Patent	Original	7/24/2001	09/912,010	9/20/2003	6,627,984	Frame/Multi-Chip Stacking of Differing Package Types	Issued. 3 1/2 year maintenance fee due 03/30/2007.	DPAC	8/3/2003
DENSE-027G	Chip Stack with Differing Chip Package Types	Patent	Divisional	10/3/2002	10/263,859			Frame/Multi-Chip Stacking of Differing Package Types	** Closed.	PTO	None
SE-027PC	Chip Stack with Differing Chip Package Types	Patent	PCT	7/9/2002	PCT/US02/21546			Frame/Multi-Chip Stacking of Differing Package Types	** Closed.	DPAC	1/24/2004
DENSE-028A	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Original	6/21/2000	09/598,373	6/11/2002	6,404,043	Panel Stacking of BGA Devices	Issued. 3 1/2 year maintenance fee due 12/11/2005.	N/A	None
DENSE-028B	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Continuation-in-Part					Panel Stacking of BGA Devices	Closed.	N/A	None
DENSE-028B1	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Continuation-in-Part	12/14/2001	10/017,553	5/20/2003	6,566,746	Panel Stacking of BGA Devices	Issued. 3 1/2 year maintenance fees due 11/20/2006.	N/A	None

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Case	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required Owner	Date Required Action Assigned
DENSE0288IG	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Divisional	12/11/2002	10/316,566			Panel Stacking of BGA Devices	** Closed.	PTO	None
DENSE-028G	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Divisional	8/6/2001	09/922,977	4/8/2003	6,344,815	Panel Stacking of BGA Devices to Form 3-D Modules	Issued. 3 1/2 year maintenance fees due 10/08/2006.	n/a	None
DENSE-028GC	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Continuation	11/8/2002	10/290,994			Panel Stacking of BGA Devices to Form 3-D Modules	** Closed.	PTO	None
DENSE-028PC	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	PCT	3/29/2001	PCT/US01/10130			Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Closed.	N/A	None
DENSE-028T1	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Taiwan	5/4/2001	90110694			Panel Stacking of BGA Devices to Form Three-Dimensional Modules	** Closed.	DPAC	2/28/2004
DENSE-029A	Flux/Underfill Incorporating Ball Spacers	Patent	Original	6/23/2000	09/602,056			Flux/Underfill Incorporating Ball Spacers	Closed.	N/A	None
DENSE-010A	Module with One Side Stacked Memory	Patent	Original	1/9/2001	09/757,155			Single Density Board with One Side Stack	Closed	N/A	None
DENSE-032A	BGA Device with Flex Flap	Patent	Original					BGA Device with Flex Flap	Closed.	DPAC	None
DENSE-033A	Heterogeneous Enhanced L-P Stack	Patent	Original					Heterogeneous Enhanced L-P Stack	** Closed.	DPAC	ASAP
DENSE-034A	Internal Detectors for Capacitive Coupling Test	Patent	Original	4/19/2002	10/126,760			Internal Detectors for Capacitive Coupling Test	Closed.	PTO	None
DENSE-035A	Socketed Stacking	Patent	Original					Socketed Stacking	** Closed	N/A	None
DENSE-037A	3-D Memory Stacking Using Anisotropic Epoxy Interconnection	Patent	Original	4/5/2001	09/826,621	10/29/2002	6,472,735	3-D Memory Stacking Using Anisotropic Epoxy Interconnects	Issued. 3 1/2 year maintenance fees due 04/29/2006.	N/A	None

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Case	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required	Date Required Action
DENSE-037D	Three Dimensional Memory Stacking Using Anisotropic Epoxy Interconnections	Patent	Divisional	3/6/2002	10/092,073			3-D Memory Stacking Using Anisotropic Epoxy Interconnects	Closed.	Owner DPAC	9/18/2003
DENSE-043A	Buried Device Stack	Patent	Original					Buried Device Stack	** Closed.	DPAC	ASAP
DENSE-044A	Slice Interconnect Structure	Patent	Original	6/3/2002	10/161,529			Slice Interconnect Structure	Pending: Awaiting Receipt of Response to Restriction Requirement	PTO	none
DENSE-044N	Slice Interconnect Structure	Patent	Provisional	6/15/2001	60/298,432			Slice Interconnect Structure	Utility Application Filed - See DENSE-044N	N/A	None
DENSE-045A	I/O Interface Structure	Patent	Original	1/4/1900	10/160,857			I/O Interface Structure	** Closed.	PTO	None
DENSE-045N	I/O Interface Structure	Patent	Provisional	6/15/2001	60/298,371			I/O Interface Structure	Utility Application Filed - See DENSE-045N	N/A	None
DENSE-046A	Retaining Ring Interconnect Used for 3-D Stacking	Patent	Original	9/20/2001	09/957,373	6/3/2003	6,573,461	Retaining Ring Interconnect Using 3-D Stacking	Issued. 3 1/2 year maintenance fees due 12/03/2006	N/A	None
DENSE-046G	Retaining Ring Interconnect Used for 3-D Stacking	Patent	Divisional	4/8/2002	10/117,836			Retaining Ring Interconnect Using 3-D Stacking	** Closed.	PTO	None
DENSE-047A	Post in a Ring Interconnect Used for 3-D Stacking	Patent	Original	9/20/2001	09/957,190	6/3/2003	6,573,460	Post in Ring Interconnect Using 3-D Stacking	Issued. 3 1/2 year maintenance fees due 12/03/2006	N/A	None
DENSE-047G	Post in a Ring Interconnect Used for 3-D Stacking	Patent	Divisional	4/5/2002	10/117,245			Post in Ring Interconnect Using 3-D Stacking	** Closed.	PTO	None
DENSE-049A	Thermal Ring Used in 3-D Stacking	Patent	Original	11/6/2001	09/994,002			3-D Stacking Using Thermal Ring	** Closed.	PTO	None
DENSE-051A	A Flex Tab for Use in Stacking Packaged Integrated Circuit Chips	Patent	Original	12/17/2001	10/024,389			Flex Tab Stacking	** Closed.	PTO	None

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DENSE-052A	CSP Chip Stack with Flex Circuit	Patent	Original	12/14/2001	10/016,939			C-S Stack with Double Sided Flex and Formed Lead	** Closed.	PTO	None
DENSE-053A	Folded Flex Circuit with z-axis Interconnect	Patent	Original					Folded Flex Circuit with z-axis Interconnect	Closed.	DPAC	None
DENSE-055A	CS-STACK	Patent	Original					CS-STACK	Closed.	N/A	None
DENSE-059A	Trench Transposer	Patent	Original	4/7/2003	10/408,517			Trench Transposer	** Closed.	PTO	None
DENSE-060A	Integrated Z-Axis Interconnect on Post Processed Chip Scale Package	Patent	Original					Integrated Z-Axis Interconnect on Post Processed Chip Scale Package	Closed.	DPAC	None
DENSE-061A	Direct Die Scale	Patent	Original					Direct Die Scale	Closed.	DPAC	None
DENSE-062A	Near Die Stack	Patent	Original					Near Die Stack	Closed.	DPAC	None
DENSE-065A	T.S.O.P. STACKING USING LASER/SPOT WELDING INTERCONNECT	Patent	Original					T.S.O.P. STACKING USING LASER/SPOT WELDING INTERCONNECT	Closed (Combined with DENSE-067A)	N/A	None
DENSE-066A	T.S.O.P. STACKING USING UNDERLEAD INTERPOSER	Patent	Original	4/7/2003	10/408,697			T.S.O.P. STACKING USING UNDERLEAD INTERPOSER	** Closed.	PTO	None
DENSE-067A	THIN SCALE OUTLINE PACKAGE STACK	Patent	Original	12/5/2002	10/310,368			THIN SCALE OUTLINE PACKAGE STACK	Response to OA due 6/24/04	PTO	6/24/04
DENSE-067B	THIN SCALE OUTLINE PACKAGE STACK	Patent	Combination-in-Part	7/14/03	10/620,157			THIN SCALE OUTLINE PACKAGE STACK	Awaiting Receipt of Response to Restriction Requirement	DPAC	None
DENSE-067S	T.S.O.P. STACK PATENT SEARCH	Patent	Search					T.S.O.P. STACK PATENT SEARCH	Patent Search Opinion Letter to client 12/31/2002.	N/A	None

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DENSE-068A	T.S.O.P. POLYIMIDE FILM STRIP STACK	Patent	Original					T.S.O.P. POLYIMIDE FILM STRIP STACK	** Closed.	DPAC	None
DENSE-069A	TRANSPOSER CONVERTER FOR MONOLITHIC TO STACKABLE	Patent	Original					TRANSPOSER CONVERTER FOR MONOLITHIC TO STACKABLE	** Closed.	DPAC	None
DENSE-070A	STAIR-STEP SIGNAL ROUTING	Patent	Original	4/21/2003	10/420,485			STAIR-STEP SIGNAL ROUTING	Awaiting Receipt of First Office Action	PTO	None
DENSE-071N	METHOD TO ACCESS SCALABLE ARRAYS OF MEMORY VIA HYPER TRANSPORT BUSES	Patent	Provisional					METHOD TO ACCESS SCALABLE ARRAYS OF MEMORY VIA HYPER TRANSPORT BUSES	Closed.	N/A	None
DENSE-072A	TSDP STACK ENHANCEMENTS	Patent	Original					TSDP STACK ENHANCEMENTS	Closed.	DPAC	None

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